

**Block Diagram** 

# **DATASHEET**

# Infrared Receiver Module IRM-V5xxM3/TR1 Series



Pin Configuration

1. OUT 2. VCC 3. GND

# Signal and noise detection TIA CGA BP DEM/ INT demodulated output signal

## **Features**

- High protection ability against EMI
- · Available for various carrier frequencies
- · min burst length (36/38 kHz): 8 cycles
- · min burst length (56 kHz): 10 cycles
- min gap length (36/38 kHz): 12 cycles
- · min gap length (56 kHz): 14 cycles
- · Low operating voltage and low power consumption
- · High immunity against ambient light
- · High immunity against TFT and PDP backlight
- · Long reception range
- · High sensitivity
- · Pb free and ROHS compliant
- · Compliance with EU REACH
- Compliance Halogen Free (Br < 900 ppm, Cl < 900 ppm, Br+Cl < 1500 ppm)</li>

#### **Descriptions**

The device is miniature SMD type infrared receiver that has been developed and designed by utilizing the latest IC technology.

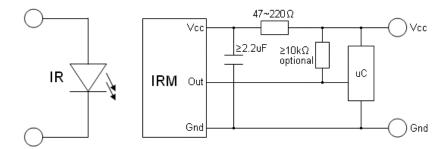
The PIN diode and preamplifier are assembled onto a lead frame and molded into an epoxy package which operated an IR filter. The demodulated output signal can directly be decoded by a microprocessor.



# **Applications**

- · Light detecting portion of remote control
- AV instruments such as Audio, TV, VCR, CD, MD, etc
- Home appliances such as Air-conditioner, Fan, etc
- · Other devices using IR remote control
- · CATV set top boxes
- Multi-media Equipment

# **Application Circuit**



The RC filter must be placed as close as possible to the Vcc and Gnd pins of the IRM.

# **Parts Table**

Model No.	Carrier Frequency
IRM-V536M3/TR1	36 kHz
IRM-V538M3/TR1	38 kHz



# Absolute Maximum Ratings (T<sub>a</sub>=25°C)

Parameter	Symbol	Rating	Unit
Supply Voltage	Vcc	6	V
Operating Temperature	Topr	-20 ~ +80	$^{\circ}\! C$
Storage Temperature	Tstg	-40 ~ +85	$^{\circ}$ C
Soldering Temperature *1	Tsol	260	°C

<sup>\*1</sup> Soldering time ≦5 seconds

# Electro-Optical Characteristics (Ta=25°C and Vcc=3.0V)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit	Condition
Current Consumption	Icc		0.4	0.6	mA	No signal input
Supply Voltage	Vcc	2.7		5.5	V	
Peak Wavelength	$\lambda_{p}$		940		nm	
Reception Distance	$L_0$	8				
	L <sub>45</sub>	5			m	See chapter
Half Angle(Horizontal)	$\Theta_{h}$		±45		deg ,Test method' *2 deg	
Half Angle(Vertical)	θν		±45			
High Level Pulse Width	$T_WH$	450		750	μs	Test signal - according to figure 1 *3
Low Level Pulse Width	$T_WL$	450		750	μs	
High Level Output Voltage	$V_{H}$	Vcc-0.4			V	
Low Level Output Voltage	V <sub>L</sub>		0.2	0.5	V	I <sub>SINK</sub> ≦2mA
Internal pull up resistor	$R_{PU}$		40		kΩ	

#### Notes:

<sup>\*2 :</sup> The ray receiving surface at a vertex and relation to the ray axis in the range of  $\theta$ = 0° and  $\theta$ =45°.

<sup>\*3 :</sup> A range from 30cm to the arrival distance. Average value of 50 pulses.



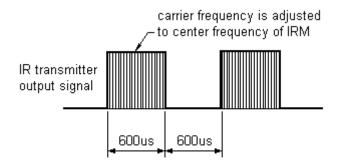
#### **Test Method**

The specified electro-optical characteristic is satisfied under the following Conditions:

- 1. Measurement environment
  - A place without extreme light reflected
- 2. External light
  - Ordinary white fluorescent lamps (Light source temperature 2856°K, Ee ≦10Lux) without high frequency modulation
- 3. Standard transmitter
  - A transmitter whose output is so adjusted as to **Vo=400mVp-p** and the output Wave form shown in Fig.-1.According to the measurement method shown in Fig.-2 the standard transmitter is specified. However, the infrared photodiode to be used for the transmitter should be  $\lambda p=940nm, \Delta \lambda=50nm$ . Also, photodiode is used of PD438B (Vr=5V)..
- 4. Measuring system According to the measuring system shown in Fig.-3

Fig.-1 Transmitter Wave Form

D.U.T output Pulse



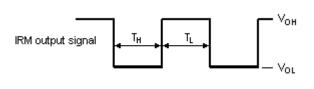


Fig.-2 Measuring Method

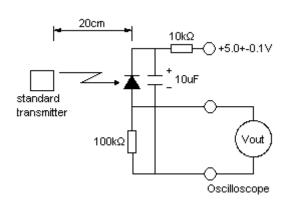
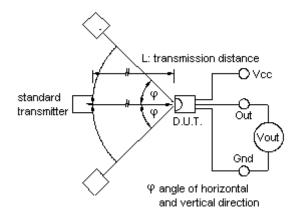
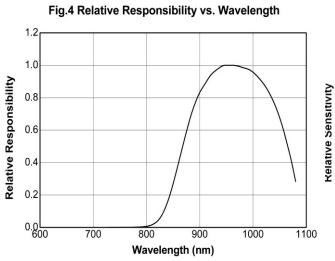


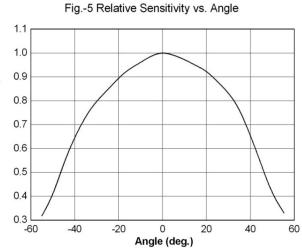
Fig.-3 Measuring System

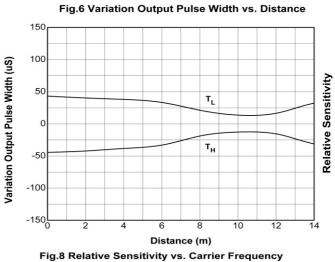


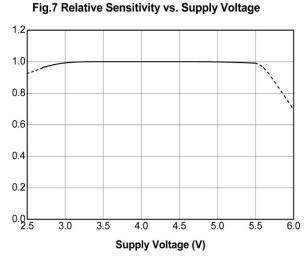


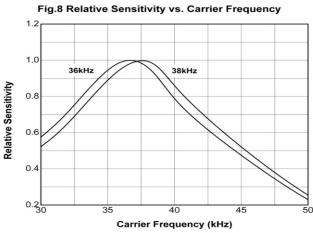
# **Typical Electro-Optical Characteristics Curves**







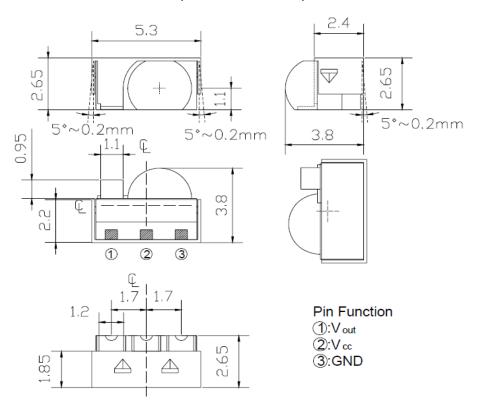






# **Package Dimenstions**

(Dimensions in mm)

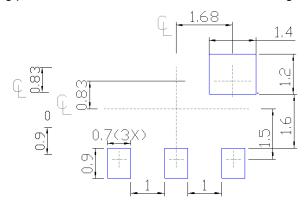


Notes:1. All dimensions are in millimeters.

2. Tolerances unless dimensions ±0.3mm.

#### Soldering patterns

The following soldering patterns are recommended for reflow-soldering



Notice: Suggested pad dimension is just for reference only. Please modify the pad dimension based on individual need.

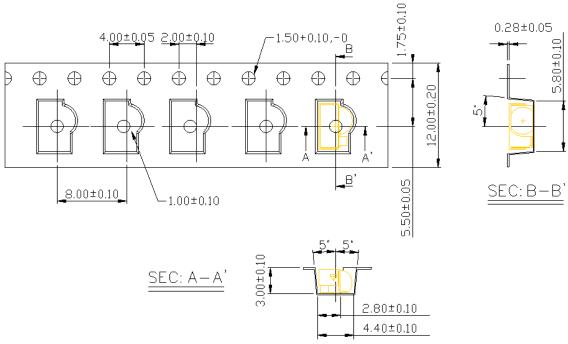


#### **Code information**

Protocol	Suitable	Protocol	Suitable
JVC	Yes	RCA	No
Matsushita	Yes	r-step <sup>2)</sup>	Yes
Mitsubishi	No	Sharp	Yes
NEC	Yes	Sony 12 bit <sup>3)</sup>	Yes
Panasonic	Yes	Sony 15 bit	No
RC5	Yes	Sony 20 bit	No
RC6 <sup>1)</sup>	Yes	Toshiba	Yes
RCMM	No	XMP-1	Yes
RCS-80	No	Continuous Code	No

- 1) Best choice depends on RC6 mode. If data low time is below 22ms, M2 is the best choice, otherwise M3.
- 2) For r-step 38kHz version M3 is the best choice, for 56kHz version only M is recommended.
- 3) If only Sony 12 bit version is used, M3 is recommended otherwise M2 is the best choice.

**Tape & Reel Packing Specifications** 



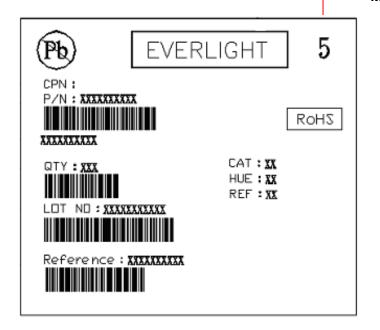
# **Packing Quantity**

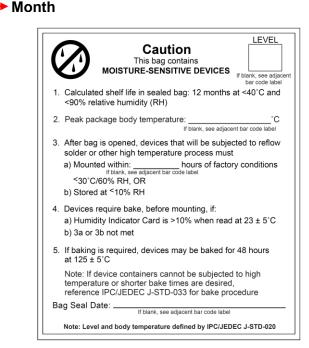
2000 pcs / Reel

5 Reels / Carton



#### Label format





Moisture Classification-storage and used condition label

# Recommended method of storage

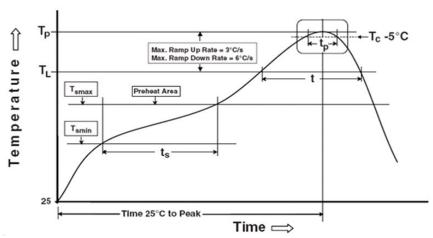
The following are general recommendations for moisture sensitive level (MSL) 4 storage and use:

- 1. Shelf life in sealed bag from the bag seal date: 12 months at 10°C ~30°C and < 90% relative humidity (RH)
- 2. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must mounted within 72 hours of factory conditions at 10°C~30°C and 60%RH.
- 3. If the moisture absorbent material (silica gel) has faded away or the IRM has exceeded the storage time. Baking treatment is required, refer to IPC/JEDEC J-STD-033 for bake procedure or recommend the conditions: 96 hours at 60°C ± 5°C and < 5 % RH.

#### **ESD Precaution**

Proper storage and handing procedures should be followed to prevent ESD damage to the devices especially when they are removed from the Anti-static bag. Electro-Static Sensitive Devices warning labels are on the packing.

# **Solder Reflow Temperature Profile**



Note: Reference: IPC/JEDEC J-STD-020D

#### **Preheat**

Temperature min (T<sub>smin</sub>) 150 °C Temperature max (T<sub>smax</sub>) 200°C Time  $(T_{smin} \text{ to } T_{smax}) (t_s)$ 60-120 seconds Average ramp-up rate  $(T_{smax} \text{ to } T_p)$ 3 °C/second max

#### Other

Liquidus Temperature (T<sub>L</sub>) 217 °C Time above Liquidus Temperature (t<sub>1</sub>) 60-150 sec 260°C Peak Temperature (T<sub>P</sub>) Time within 5 °C of Actual Peak Temperature: T<sub>P</sub> - 5°C 30 s Ramp- Down Rate from Peak Temperature 6°C /second max. Time 25°C to peak temperature 8 minutes max. Reflow times 3 times

#### Note:

- 1. Suggest that reflow soldering should not be done more than two times.
- 2. When soldering, do not put stress on the IRM device during heating.
- 3. After soldering, do not warp the circuit board.



#### **DISCLAIMER**

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